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**DIE ATTACH**  
**ME8418-SC**

**Rapid Curing**  
**High Strength**  
**Electrically Conductive**  
**Epoxy Paste Adhesive**

**IDEAL FOR:**

Low Temperature Die-Attach  
 Smart Card Die and Module Attach

**DESCRIPTION:**

ME8418-SC is a rapid curing version of ME8418-FP-LV. This silver filled paste is solvent free, electrically and thermally conductive. It is designed for automated, online die attach processing.

**TYPICAL PROPERTIES\***

Electrical Resistivity ( 100 °C/ 60 minute )	<4x10 <sup>-4</sup> ohm-cm
Dielectric Strength (Volts/mil)	N/A
Glass Transition Temp.(°C)	90 ±10%
Current Carrying Capabilities	>50 Amp/mm <sup>2</sup>
Lap-Shear Strength	N/A
Device Push-off Strength	>3200 psi >22.0 N/mm <sup>2</sup>
Hardness (Type)	80 (D) ±10%
Cured Density (gm/cc)	3.5 ±10%
Thermal Conductivity	28 Btu-in/hr-ft <sup>2</sup> -°F ±10% 4.0 W/m-°C ±10%
Linear Thermal Expansion Coeff. (ppm/°C)	40 ±15%
Maximum Continuous Operation Temp. (°C)	<150
Avg. Viscosity(5 rpm, 24°C)	10,000 cp ±20% TI=4.0

\* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

**AVAILABILITY:**

ME8418-SC is available in syringes or in jars.

**APPLICATION PROCEDURES:**

- ( 1 ) Thaw for 30 minutes before opening jar or using syringes.
- ( 2 ) Dispense adhesive onto clean substrate with a suitable pattern to assure full die coverage.
- ( 3 ) Cure according to one of the recommended schedules.

**CURE SCHEDULES:**

Temperature	Time	Pressure
	<120	
85°C	min	
100°C	<60 min	
125°C	<20 min	
150°C	<10 min	

**SHELF LIFE:**

Storage temperature	Shelf Life
-40°C	1 yr
25°C	5 day

**CAUTION:** This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.  
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